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3D/69/RM

1999-12

**INTERNATIONAL ELECTROTECHNICAL COMMISSION
COMMISSION ELECTROTECHNIQUE INTERNATIONALE**

**TECHNICAL COMMITTEE NO. 3: DOCUMENTATION AND GRAPHICAL SYMBOLS
SUB-COMMITTEE NO. 3D: DATA SETS FOR LIBRARIES**

Unconfirmed Minutes of the meeting of SC3D on October 27th, 1999 in Kyoto, Japan.

Present:

Chairman: Dr. D.E. Radley (United Kingdom)

Secretary: Mr. P.G. van Reekum (Netherlands)

Central Office:

COUNTRY	DELEGATES	COUNTRY	DELEGATES
China	Mr. Yunchi Xu	Japan	<u>Prof. Mikio Takagi</u> Mr. Satoshi Ito
Finland	Mr. Tapio Viitanen		Mr. Keiji Namimoto
France	Mr. Jacques Bodin		Mr. Mitsuru Takahashi
Germany	<u>Mr. Dietmar Borries</u> Mr. Wolf-Dieter Kisselmann	Netherlands	<u>Mr. Arnold Gehner</u> Mr. Frans van Noesel
	Mr. Fritz Reuter		

Observers:

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I. Opening of the meeting

The Chairman, Dr. Radley, opened the 9th meeting of SC3D, thanked the Japanese National Committee for hosting the meeting and wished the delegates a good and constructive meeting. He thanked the delegates of the Japanese National committee for the excellent TC3 reception on Tuesday. It was planned to finish the meeting before 16.00 hrs because representatives of SC3D and officers of the IEC Central Office will have a meeting at 16.00 hrs regarding IPR and copyright issues.

II. Approval of the (Revised) draft Agenda, document 3D/54/DA-1

The agenda was approved without modification.

III. To note the minutes of the meeting of SC3D held in Charlottelund November the 12th, 1998, document 3D/65/RM

Since no comments were received within three months after publication, the minutes were noted as circulated.

There were no actions arising from the minutes that were not covered by the agenda.

IV. To receive a report from the Chairman and Secretary regarding the harmonization of efforts and results with ISO TC184/SC4/WG2 'Part libraries', and possible implications on the work in both committees.

The report prepared for this meeting, **document 3D(Kyoto/secretariat)02**, is attached as annex A to these minutes. The report was noted.

Mr. van Noesel gave some additional information to the report. During a special meeting between Dr. Radley, Mr. van Noesel and Prof. Pierra the required extensions in the EXPRESS model by SC3D were discussed. It was proposed that the common EXPRESS model should not be changed and that the required extensions be published in a new part 5 of IEC 61360 using the same structure as the ISO 13584-24 part.

V. Status overview of the IEC 61360 documents: "Principles and methods for defining standard data element types with associated classification scheme for electric components".

5.1 61360-1: Definitions - Principles and methods

The Working Group is working on a new proposal which will be circulated as a Committee Draft for Voting by the IEC Central Office by the end of the year. For more details see point 6 of the agenda.

5.2 61360-2: EXPRESS Dictionary schema

A new version of clause 8 of IEC 61360-2 will be issued as soon as the final checks on the templates and examples are completed. For more details see point 6 on the agenda

5.3 61360-3: Maintenance and Validation procedures

A letter was send to the candidates for the Maintenance Agency to inform them of what is expected from such an Agency. Two replies have been received up to now. For more details see point 6 on the agenda.

5.4 61360-4: IEC Reference Collection of standard data element types, component classes and terms.

The first collection of requests for new/updated data element types was considered. The requests will be collected and published as a supplement to IEC 61360-4 after approval. For more details see point 6 on the agenda.

VI To receive a report from:

- **SC3D/WG1 - Classification and coding of component packages -, and**
- **SC3D/WG2 - Classification of components and definition of technical data elements, document 3D(Kyoto/WG 1&2)05**

The Chairman thanked the secretary for preparing this report, attached as annex B to these minutes.

Working Group 2

A brief overview was given by Dr. Radley regarding the development and discussions of the proposal for a new version of IEC 61360-1. The requirements for new and more complex data types besides the data types in the current IEC 61360-1 were discussed. These additions will cause extensions in the EXPRESS model of IEC 61360-2. In consultation with Prof. Guy Pierra, convenor of ISO/TC184/SC4/WG2, it was decided that the common ISO/IEC EXPRESS model should not be changed since it is already in use in many applications world-wide. Therefore it was proposed to make a new part 5 in IEC 61360 series containing the required extensions and accompanying templates and examples. This new part 5 will also include the new modelling of terms. The need for this new part will be reported in the report to the Committee of Action and incorporated in the programme of work of SC3D. A first draft will be discussed in the next Working Group meeting in March 2000.

It was proposed to make the introductory clause in IEC 61360-1 more helpful to potential users. It was agreed that a new proposal will be send to the Central Office for circulation as a Committee Draft for Voting by the end of the year.

Several organisations have expressed their interest taking up the role as Maintenance Agency for the IEC Reference Collection. A letter was send to the candidates for the Maintenance Agency to inform them about the tasks as foreseen performed by such an agency. Two replies were received until now.

The consequences of using the IT infrastructure at the Central Office for the maintenance activity and having the Maintenance Agency elsewhere has to be investigated and discussed with officers of the Central Office.

Note of the Secretary: Later in the week we were informed by the Technical Director of IEC that the IEC Central Office intends to act as the Maintenance Agency for the IEC reference collection.

A new letter was prepared and sent to the Central Office for circulation as an Administrative Circular to the IEC Technical Committees and National Committees asking for help in the validation process.

The first collection of requests for new/updated data element types shows that a lot of them were not compliant with the rules of IEC 61360-3. Therefore it was proposed to develop templates to check the completeness of the requests and to help requestors to fill in the mandatory fields and a guide will be prepared to help requestors in using the templates. The templates will be tested before the Working Group meeting March 2000 and evaluated during this meeting. The requests for new data element types will be collected and published as a supplement to IEC 61360-4 after approval.

Working Group 1.

A new proposal for document: Classification and coding of shapes of electric components for placement on printed wiring boards is in preparation and will be discussed in the next Working Group meeting. After approval by the Working Group the document will be sent to the Central Office for circulation as a second Committee Draft for comments.

VII. Organization of future work

7.1 Activities of the SC3D Working Groups.

7.1.1 Working Group 1 -- "Classification and coding of component packages"

The International standard for Classification and coding of shapes of electric components for placement on printed wiring boards will be issued in 2001.

The amount of work spent in this Working Group is less than in Working Group 2 in which the first priority is to prepare a new IEC 61360-1.

7.1.2 Working Group 2 -- "Classification of components and definition of technical data element types"

The second edition of International Standard for IEC 61360-1 will be issued by the end of next year.

A new clause 8 for IEC 61360-2 will be issued by the end of 1999.

A supplement to IEC 61360-4 will be issued by the end of 2000.

A new part 5 will be issued by the end 2000.

7.1.3 To discuss the need for the erection of additional Working Group(s)

For the time being there is no foreseen need for new Working Groups to be established. It is expected that the existing Working Groups can take on the work for the immediate future.

VIII To discuss the Strategic Policy Statement, document 3D(Kyoto/secretariat)06

The strategic policy statement has to be modified and extended in several places. The delegates agreed that the chairman and secretary would take care of this.

8.1 To discuss the Programme of work, document 3D/55/PW

As some of the documents referenced have been superseded, the Programme of Works has to be updated. The secretary will send the updated information to the Central Office.

IX Liaisons with:

- **other Committees of IEC, ISO, CEN/CENELEC;**
- **SI2/ECIX (former Pinnacles)**
- **establishment of a liaison with E-Cals (part of N-Cals)**

The established contacts with IEC/TC93, ISO/TC184/SC4/WG2, CIREP and ECIX were continued.

It was agreed to explore the setting up of a formal liaison with IEC SC47D in connection with the work of SC3D/WG1 in classification and coding of component packages. Mr Gehner agreed to act as liaison officer.

The Japanese E-CALS project has used the IEC dictionary and methodology as the basis for its dictionary. The E-CALS project will be finished March 2000 and will be taken over by EIAJ. It was agreed to establish a liaison with this activity and Mr. Tanaka agreed to act as liaison officer.

The CIREP project was concluded successfully in March, having used the IEC 61360-4 dictionary as the basis for its component modelling and capture activities. It was agreed to establish a liaison with the new MERCI project, successor to CIREP, and Mr Kisselmann agreed to continue as liaison officer.

A liaison with RosettaNet was discussed. It was agreed that for the time being a liaison is not needed. It was agreed to follow the developments and as soon as appropriate the need for a liaison will be considered.

X Liaison reports from:

10.1 Tapio Viitanen on TC93, document 3/552/INF

The report of Mr. Viitanen was noted and is attached as annex C to the minutes.
It was noted that the copyright problems with EDIF have been resolved and agreements have been established.

10.2 Wolf-Dieter Kisselmann on CECC/WG-CAD - CIREP, document 3D(Kyoto/Kisselmann)07

The report of Mr. Kisselmann was noted and is attached as annex D to the minutes.
As the work items of the CECC WG-CAD has been taken over by the ESPRIT CIREP/MERCI project and the IEC 61360 related activities, the CECC WG-CAD has been disbanded.

10.3 Frans van Noesel on CENELEC TC217 and SI2/ECIX, document 3D(Charlottelund/vNoesel)08

The report of Mr. van Noesel was noted and is attached as annex E to the minutes.

XI To prepare a report for the TC3 meeting of October 24, 1997, document3(Charlottelund/SC3D)6.

It was agreed that the Chairman and the Secretary will produce this report.

XII Any other business.

The questions of copyright and IPR (Intellectual Property Right) of IEC standards and their contents were discussed. The needs for information exchange in electronic form by the global industry is increasing and with that the protection of copyright and IPR need to be discussed frequently and will become more complex. No firm conclusions were reached but it was agreed that this topic needs further discussion within IEC Central Office. SC3D considers that copyright and IPR issues belong to the responsibility of the IEC Central Office.

XIII Date and place of the next meeting.

The next SC3D meeting will be held in Stockholm (Sweden), September 2000 in conjunction with the General meeting. The meeting in 2001 will probably held in Firenze (Italy).

XIV Closure of the meeting

The chairman thanked the delegates for their attendance and contribution to this meeting. He thanked the Japanese National Committee and its staff once more for the facilities provided and the excellent secretariat support during the meeting. He wished the delegates a safe journey home and closed the meeting.



Peter van Reekum
secretary IEC SC3D

Annex A



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3D(Kyoto/secretariat)02
September 1999

INTERNATIONAL ELECTROTECHNICAL COMMISSION

SUB-COMMITTEE NO. 3D: DATA SETS FOR LIBRARIES

Report from the ad-hoc Joint Working Group: IEC/SC3D -- ISO/TC184/SC4/WG2

Members of both SC's met each other on a regular base during the ISO/TC184/SC4 (STEP) meetings in January 1999 San Francisco (USA), June 1999 Lillehammer (Norway). In this meeting the topics of common interest in both committees was discussed.

Besides these meetings Dr. Radley and Mr. F. van Noesel had a two days intensive meeting with prof. G. Pierra in Poitiers (France) in order to define solutions for the by SC3D required extensions in the EXPRESS model. For almost all topics a solution was agreed.

Both committees (the ISO STEP Plib community and IEC SC3D) expressed their intention to continue the fruitful co-operation.

A handwritten signature in black ink, appearing to read 'Peter van Reekum', written in a cursive style.

Peter van Reekum

Annex B



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3D(Kyoto/WG)05
October 1999

INTERNATIONAL ELECTROTECHNICAL COMMISSION

TECHNICAL COMMITTEE NO. 3: DOCUMENTATION AND GRAPHICAL SYMBOLS

SUB-COMMITTEE NO. 3D: DATA SETS FOR LIBRARIES

Report from Working Group 1 and 2

Report from the convenor of:

SC3D Working Group 1 - Classification and coding of component packages

SC3D Working Group 2 - Classification of components and definition of technical data elements

1. scopes:

1.1. WG1:

to prepare standards for classification and coding of electric components according to key mechanical characteristics for use on printed wiring boards in design and mechanical handling.

1.2. WG2:

Using existing definitions, terminology and practices to set standards to prepare definitions for technical data element types that can be used:

1.2.1. to describe electric components;

1.2.2. to establish subsets selected from the list of data elements suitable for characterizing individual component classes;

1.2.3. to prepare a standard scheme for classification of components according to function and technology as appropriate.

2. membership:

No changes in the list of memberships since the meeting of SC3D in Charlottelund, November 1998.

The active participation of Japan was welcomed.

3. Work since Charlottelund:

Two meetings since the Charlottelund meeting, Muenchen March 1999 and Sheffield June 1999. From these meetings informal notes from the convenor are available on demand or from the SC3D homepage.

Both Working Groups held joint meetings.

Packages: Working Group 1 is working on a new committee draft.

IEC 61360-1: Working Group 2 is working on a construct for complex data types that will not influence the common EXPRESS model. This construct will be incorporated together with the decisions as stated in 3D/66/CC in the next committee draft.

IEC 61360-2: The new clause 8 is in preparation together with Prof. Guy Pierra (ISO TC/SC4/WG2)

IEC 61360-3: A letter is send to the candidates for the maintenance Agency to explain what is

expected from such an Agency.

An administrative Circular is send to the Technical Committees and National Committees for asking their co-operation in the Validation process.

IEC 61360-4: Working Group 2 is working on the supplement to IEC 61360-4. The first set of requests has been collected and the rework has been started.

4. Quotations from the meeting of the SC3D Working Group 1&2:

4.1. Working Group 2:

- 4.1.1. The new proposal for the IEC 61360-1, working group document 3D/WG/013, was discussed.
- 4.1.2. Besides the two existing data types in IEC 61360-1, new and more complex data types such as 2D, 3D, tolerance and complex number types are required.
- 4.1.3. In co-operation with Prof. Guy Pierra who is convenor of ISO/TC184/SC4/WG2 it was decided not to change the Common ISO/IEC EXPRESS dictionary model because it is already in use in many applications. A solution was found in making use of the class_instance_ type that is already in the EXPRESS model.
- 4.1.4. Using the class instance type references/links can be made from a DET definition to any class in the classification structure. Using this construct, tolerances, 2D, 3D and complex number can be handled. This construct can also meet the requirements from Norway and Germany for estimated-, calculated-values, arrays, matrices etc. It was agreed by the Working Group that Dr. Donald Radley will introduce this construct also in the SC3D meeting.
- 4.1.5. A new clause 3.4.5 was agreed upon in which the new data_types are defined.
- 4.1.6. It was agreed to add at least two examples in an annex to illustrate the working of this linking construct.
- 4.1.7. The topic of extending the EXPRESS model by introducing the same methodology for terms as for DETs and Classes will be discussed with Prof. Guy Pierra.
- 4.1.8. It was decided to launch part 5 of IEC 61360 containing all aggregations of the common ISO/IEC EXPRESS information model. This part 5 should be comparable with the corresponding ISO 13584-24 part.
- 4.1.9. The completeness of the requests for new DETs differ considerably. It was decided to have a quick manual check on the completeness of the mandatory data. If this requirement is not fulfilled the requests will be returned to the sender with reasons why.
The complete ones will be brought into a standard format and set to the secretary of the relevant product committee to be checked on correctness. The results will be published in an addendum to IEC 61360-4.
To help requestors a new template will be offered. Mr Sumio Araki and Mr. Fritz Reuter will produce proposals. Mr. Frans van Noesel will write a guide about how to fill the required fields.
- 4.1.10. The letter intended to inform candidate maintenance agencies has been send out.
Two replies have been received up to now. CODUS Ltd. will formerly state to the CO that they resign from acting as MA for IEC 61360-4. Before 2000 the SC3D national committees will be asked to agree with a proposal for the MA to be appointed later by the IEC Council.
- 4.1.11. The consequences of using the IT infra structure for the maintenance activity at the CO and having the MA itself elsewhere will be investigated and discussed with IEC officers.
- 4.1.12. The letter to the product committees regarding the Validation groups has just been send out as Administrative Circular.

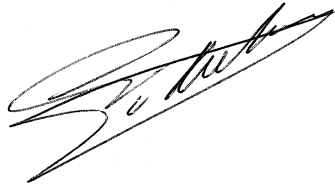
5. Working Group 1:

It is expected that a new CD, in which all decisions of WG1 from the last few meetings are incorporated, can be issued after the March 2000 meeting of Working Group 1.

Planned Working Group meetings

Next Working Group meetings are scheduled.

March 2000	probably Muenchen, Germany in conjunction with the IEC TC3 preparatory meeting for the 2000 TC3/SCs meetings.
June 2000	Eindhoven, the Netherlands
September 11 th to 22 nd 2000	Stockholm, Sweden in conjunction with the General Meeting
February 2001	Sheffield, United Kingdom.



Peter van Reekum
Convenor SC3D / WG 1&2
October 27th, 1999

Annex C

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3/552/INF

1999 – 09 Rev

1. **INTERNATIONAL ELECTROTECHNICAL COMMISSION**
2. **Technical Committee No. 3 Documentation and graphical symbols**
3. **Report to the Kyoto meeting from IEC TC 93: Design Automation**

TC93 had **September 1998 meeting in London** and next plenary meeting will be **in Arlington, USA 1999-09-22...24**. Also several WGs will meet there. Report from those meetings can be given at TC3 meeting in Kyoto. After the TC3 meeting in Charlottelund several TC 93 projects have progressed quite well. The following overview lists those ongoing activities relevant to IEC TC3.

1. Documents distributed within IEC TC 93
 - 93/90/CD Design automation reference model - Core conceptual model of the electronics domain (CCM) [CDV IEC 62016 is under preparation.] The project is related to harmonisation of connectivity models with ISO 10303-210 (and 212) and EDIF
 - IEC 61690-1 Ed. 1.0 Electronic design interchange format (EDIF) - Part 1: Version 3.0.0 [APUB IEC 61690-1, delayed because of copyright negotiations] **has been given to IEC**
 - IEC 61690-2 Ed. 1.0 Electronic design interchange format (EDIF) - Part 1: Version 4.0.0. [APUB IEC 61690-2, delayed because of copyright] **has been given to IEC**
TC 93 has decision to made during preparation of the next edition of IEC61690 co-operation with respect to get harmonization between IEC61690 series and the relevant STEP APs, primarily ISO 10303-210.

In Arlington **1995** 93/51/RM Unconfirmed Minutes of the meeting held in Arlington, Virginia (U.S.A.) from 4th to 6th December 1995:

Resolution 95-1: (partly copied) TC 93 requests its WG 1 to progress (CCM) when received from EIA EDIF and CFI and prepare it for submission as CDC...EIA is recognised as the feeder organisation. This will be a foundation for future work in electronics design standardization and will significantly contribute to the interoperability of future work.

Resolution 95-2: WG1 should plan to map both AP210 and EDIF 400 against the CCM.

London : WG1 and WG3 of TC93 will undertake no further efforts in harmonization between EDIF and AP210 until WG1 is convinced that AP210 supporters are devoting sufficient resources to the interoperability effort.

Yes 5 No 2 Abstain 1

AR (2.1) Prof. Hilary Kahn - publish a short educational document as a technical report - "Consideration of modeling and its use in the standardization process" by June, 2000.

AR (4.7): Prof. Kahn to submit an NWIP proposal for an extension to EDIF based on the ECCE work by December 30, 1999.

AR (9.1): Mr. Ledenbach to include the EXPRESS v.1 (ISO 10303-11:1994) question of principle to the Committee of Action in the TC93 report by October 15, 1999. **DONE**

- 93/67/CDV Electronic behavioural specifications of digital integrated circuits - Part 1: I/O Buffer Information Specification (IBIS, Version 2.1) (future IEC 62014-1)
 - **(Arlington) CD about IEC 62015-1 Design automation - Chip Hierarchical Design Systems Technical (CHDStd) by November 1, 1999.**

- PWI 93-1 Ed. 1.0: 93/67/NP Models of integrated circuits for EMI behavioral simulation (level zero project PWI 93-1 Ed. 1.0 future IEC 62014-3)

- PWI 93-2 Ed. 1.0: Library standard architecture (level zero project, future TR IEC 62014-2)
 - **PWI 93-7 Ed. 1.0: 93/73/NP Libraries of reusable parts for electrotechnical products (level zero project.Deleted in Arlington.**

One project related to rejected 93/80/NP Electronic CAD to CAM Exchange is under preparation as PAS-standard by TC 52 52/827/PAS (IEC-PAS 62119). See also 52/831/FDIS, IEC 61182-10.

2. Participation of IEC TC93 in Sector Board 3 / related ACET issues

- New chairman Mr. J. Heaton represented TC93 in Sector Board 3, Industrial Automation meeting Jan. 1999. The interoperability between TC 93 standards and others standards and tools for the design of automation system (not purely electronic) could not solved.

- Recommendation 9904/6 of ACET meeting 1999-04-22: ACET welcomes the planned launch meeting of the Electronic Design Automation Harmonization Group (EDAHG), intended to take place in June 1999.
Note. Report from this meeting will be discussed in TC93 Arlington meeting.

New projects discussed I Arlington: “

- **Terms,**

T. Viitanen
Liaison Officer



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3D(Kyoto/Kisselmann)07
October 1999

INTERNATIONAL ELECTROTECHNICAL COMMISSION

TECHNICAL COMMITTEE NO. 3: DOCUMENTATION AND GRAPHICAL SYMBOLS

SUB-COMMITTEE NO. 3D: DATA SETS FOR LIBRARIES

Report of the liaison with CIREP Esprit Project

Main CIREP meetings held during the reporting period are the following:

- 1st CIMT/CICT Workshop in Hagen, November 25th and 26th, 1998
- 2nd CIMT/CICT Workshop in Hagen, February 1st and 2nd, 1999
- Final CIREP Review March 19th, 1999 in Paris

Status after the end of CIREP

The following achievements have been produced in the CIREP project:

- Prototype implementations for capture and storage of information according to IEC61360 and ISO13584 (PLIB) is available
- The complete delivery chain for component information from the manufacturer to the end user's CAD database has been demonstrated
- A methodology for organising component information has been defined and proven by means of examples from the electronic domain (which were selected as most complex component classes with respect to their structural variety)
- Liaisons to other standards groups have been built, among them ECIX, ECALS, a.o.

Thus, CIREP has produced demonstrators which show the validity of the CIREP approach and of the usability of concepts of the standards IEC61360 and ISO13584 (PLIB). To make CIREP a success in the market field, a follow-up ESPRIT Project was defined: MERCI

3.1. OBJECTIVES OF MERCI

The flow of component information from component manufacturers to users is important for the cost effectiveness of product development.

MERCI will build a commercial service agency and the required underlying software infrastructure to facilitate this information flow. The service agency will use standards (P-Lib, IEC61360, PCIS) and make them interoperable. It will support the transformation from data sheets and legacy data into the standard formats and from standard formats into libraries of CAD systems.

By mechanisms for the exchange of change information and the electronic commerce of components, it will strengthen the supplier-customer relationships.

MERCI will thus continue the engagement in the area of component information management standards (P-Lib, IEC61360) and implementations (CIREP project).

Note:

As the work items of the CECC WG-CAD has been taken over by the ESPRIT CIREP/MERCI project and the IEC 61360 related activities, it has been decided to disband the CECC WG-CAD.

Wolf-Dieter Kisselmann
Kyoto, October 27th, 1999

Annex E



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3D(Kyoto/vnoesel)08
October 1999

INTERNATIONAL ELECTROTECHNICAL COMMISSION

TECHNICAL COMMITTEE NO. 3: DOCUMENTATION AND GRAPHICAL SYMBOLS

SUB-COMMITTEE NO. 3D: DATA SETS FOR LIBRARIES

Report of the liaison with Cenelec TC 217 and SI2-ECIX

1. Cenelec TC 217

The earlier mentioned "on hold situation" still applies. Meetings were neither planned nor hold. The documents regarding "Electronic Data Book Interchange Format (CLC Project: 5911)" originated by the SI2 ECIX team R217-015 and R217-016 are accepted and published as technical report while the documents ENV 50247-1 and ENV 50247-2 are accepted and published as European standards.

No further information is available on open activities.

2. SI2 - ECIX

PCIS - CIDS: the development under the **ECIX** project of **PCIS** (Pinnacles Information Dictionary Standard) and **CIDS** (Component Information Dictionary Standard) have been continued..

The project is at this moment looking for how to continue with this work in the coming years. They aim clearly for a public available standard (free available on the internet).

Participation as a project under RosettaNet is considered, now RosettaNet also wants to deal with (electric) component information.

Discussions with IEC Central Office have been started to look for co-operation in order to avoid a duplication of work and to solve Copyright and IPR issues.

The series of IEC 61360-4 standards as produced by SC3D have been presented.

A small ESPRIT project (JComp) is still running which should result in an interchange of dictionary data between the data formats of ECIX and CIREP.

A handwritten signature in black ink, appearing to read 'Frans van Noesel', written over a horizontal line.

Frans van Noesel
September 27th, 1999